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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
Jean Wang	04/25/2007
Francis Ko	04/25/2007
Ping-Hsu Chen	04/26/2007
Henry Lo	04/25/2007
Chih-Wei Lai	04/25/2007

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	
Street Address:	No. 8, Li-Hsin Road 6	
Internal Address:	Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
Postal Code: 300-77		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11744107

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 24061.873

PATENT REEL: 019245 FRAME: 0676

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OF \$ 40

NAME OF SUBMITTER:	David M. O'Dell	
Total Attachments: 3		
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PATENT REEL: 019245 FRAME: 0677

Docket No.: 2006-0900 / 24061.873

Customer No.: 42717

ASSIGNMENT

WHEREAS,	we,
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(1)	Jean Wang	of	3F-4, University Rd. Hsin Chu, Taiwan, R.O.C.
(2)	Francis Ko	of	5F-4, No. 92, Jingcheng Rd., West District Taichung City 403, Taiwan, R.O.C.
(3)	Ping-Hsu Chen	of	2F, No. 6, Peiying St. Hsinchu City 300, Taiwan, R.O.C.
(4)	Henry Lo	of	7F-6, No. 39, Chien Chung Rd. I Hsinchu, Taiwan, R.O.C.
(5)	Chih-Wei Lai	of	3F, No. 6, Lane 86, Ho-Ping Rd. Hsinchu City 300, Taiwan, R.O.C.

have invented certain improvements in

PREDICTION OF UNIFORMITY OF A WAFER

for which we have executed an application for Letters Patent of the United States of America,

of even date filed herewith; and

X filed on May 3, 2007 and assigned application number 11/744,107; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States

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of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:

Jean Wang

Residence Address:

3F-4, University Rd.

Hsin Chu, Taiwan, R.O.C.

Dated: 4/15/0

Intentor Signature

Inventor Name:

Francis Ko

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Taichung City 403, Taiwan, R.O.C.

Des 4/20/07

Inventor Signature

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PATENT REEL: 019245 FRAME: 0679

Docket No.: 2006-0900 / 24061.873

Customer No.: 42717

Inventor Name:

Ping-Hsu Chen

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4/26/07. Dated:

Prny- HSu Chem Inventor Signature

Inventor Name:

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Dated: 4/24/107

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RECORDED: 05/03/2007

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TOTAL P.08